| L Number |         | Search Text  | DB                     | Time stamp   | 16.10 |
|----------|---------|--|------------------------|--------------|-------|
| -        |         | integrated adj circuit and package and metal adj substrate                       | USPAT;<br>US-PGPUB;    | 2003/05/14   | 16:18 |
|          |         |  | EPO; JPO;              |              |       |
| i        | i       |  | DERWENT;<br>IBM TDB    |              |       |
| _        | 6732954 | "12" ans first adj region and second adj   | USPAT;                 | 2003/05/13   | 16:40 |
|          |         | region   | US-PGPUB;              | 1            |       |
|          | !<br>   |  | EPO; JPO;              |              |       |
|          |         |  | DERWENT;<br>IBM TDB    |              |       |
| _        | 0       | ((integrated adj circuit and package and   | USPAT;                 | 1 2003/05/13 | 16:40 |
|          |         | metal adj substrate) and substrate near  | US-PGPUB;              |              |       |
|          |         | core) and first adj region and second adj  | EPO; JPO;              | İ            |       |
| ĺ        |         | region   | DERWENT;               |              |       |
| - :      | 12      | (integrated adj circuit and package and  | IBM_TDB<br>  USPAT;    | 2003/05/13   | 16.41 |
|          | !       | metal adj substrate) and substrate near  | US-PGPUB;              | 2003/03/13   | 10.11 |
|          |         | core   | EPO; JPO;              | !            |       |
|          |         |  | DERWENT;               | !            |       |
|          | 10      | ((integrated adj circuit and package and   | IBM_TDB<br>USPAT;      | 2003/05/14   | 12.20 |
| -        | 1 12    | ((integrated adj circuit and package and metal adj substrate) and substrate near | US-PGPUB;              | . 2003/03/14 | 12:39 |
|          |         | core) and first and second   | EPO; JPO;              | :            |       |
|          | )<br>   |  | DERWENT;               |              |       |
|          | 0406    | 4057 (601 670) gov g   | IBM_TDB                |              | 10 27 |
| - '      | 2496    | (257/691,678).CCLS.  | USPAT;<br>US-PGPUB;    | 2003/05/14   | 12:3/ |
|          |         |  | EPO; JPO;              |              |       |
|          |         |  | DERWENT;               |              |       |
|          |         |  | IBM_TDB                | 0000105111   |       |
| -        | 1       | ((257/691,678).CCLS.) and ((metal adj  | USPAT;                 | 2003/05/14   | 12:39 |
| ,        |         | substrate) with core)  | US-PGPUB;<br>EPO; JPO; |              |       |
|          |         | 1  | DERWENT;               | ,            |       |
|          |         |  | IBM_TDB                |              |       |
| -        | 1       | ((257/691,678).CCLS.) and package and  | USPAT;                 | 2003/05/14   | 12:39 |
| ,        | •       | ((metal adj substrate) with core)  | US-PGPUB;<br>EPO; JPO; |              |       |
|          |         | •  | DERWENT;               |              |       |
|          |         |  | IBM_TDB                |              |       |
| -        | 0       | ((257/691,678).CCLS.) and ((integrated adj                                       | USPAT;                 | 2003/05/14   | 12:40 |
|          | ı       | circuit and package and metal adj<br>substrate) and substrate near core) and     | US-PGPUB;<br>EPO; JPO; |              |       |
|          |         | first and second   | DERWENT;               | 1            |       |
|          |         |  | IBM TDB                |              |       |
| -        | 1       | ((257/691,678).CCLS.) and package and  | USPAT;                 | 2003/05/14   | 12:42 |
|          |         | ((metal adj substrate) with core)  | US-PGPUB;              |              |       |
|          |         |  | EPO; JPO; DERWENT;     |              |       |
|          |         |  | IBM TDB                |              |       |
| -        | 40      | ((257/691,678).CCLS.) and package and  | USPAT;                 | 2003/05/14   | 12:47 |
|          |         | (metal adj substrate)  | US-PGPUB;              |              |       |
|          |         |  | EPO; JPO; DERWENT;     |              |       |
|          |         |  | IBM TDB                | 1            |       |
| _        | . 2     | (((257/691,678).CCLS.) and package and   | USPĀT;                 | 2003/05/14   | 12:43 |
|          |         | (metal adj substrate) ) and substrate near                                       | US-PGPUB;              | i            |       |
|          |         | core   | 'EPO; JPO;             |              |       |
|          |         |  | DERWENT;<br>IBM TDB    |              |       |
| _        | 9       | ((257/691,678).CCLS.) and package and  | USPAT;                 | 2003/05/14   | 13:23 |
|          | ,       | (metal adj substrate) and core   | US-PGPUB;              | , 3 0 , _ 1  |       |
|          | 1       | ]<br>!   | EPO; JPO;              | 1            |       |
|          | 1<br>1  |  | DERWENT;               | İ            |       |
|          | 2554    | (438/106,121).CCLS.  | IBM_TDB<br>USPAT;      | 2003/05/14   | 13.22 |
|          | 2554    | (430/100/121/.0015.  | US-PGPUB;              | 2003/03/14   | 17.66 |
|          |         |  | EPO; JPO;              |              |       |
|          |         |  | DERWENT;               |              |       |
|          | !       | İ  | IBM TDB                |              |       |

|        |        |   |                         | 2.         |         |
|--------|--------|---|-------------------------|------------|---------|
| [-     | 6      | ((438/106,121).CCLS.) and package and   | USPAT;                  | 2003/05/14 | 13:23   |
|        |        | (metal adj substrate) and core  | US-PGPUB;               |            | :       |
| j      |        |   | EPO; JPO; DERWENT;      |            | ;       |
|        |        |   | IBM TDB                 |            | 1       |
| : -    | 287    | package and (metal adj substrate) and core  | USPĀT;                  | 2003/05/14 | 13:23   |
|        |        | -   | US-PGPUB;               |            |         |
|        |        |   | EPO; JPO;               | ;          |         |
| ;<br>  |        |   | DERWENT;<br>IBM TDB     | 1          |         |
| _      | 25     | package and ((metal adj substrate) with   | USPAT;                  | 2003/05/14 | 13:26   |
|        |        | core)   | US-PGPUB;               |            |         |
|        |        |   | EPO; JPO;               |            |         |
|        |        |   | DERWENT;                | •          |         |
| _      | 4      | package and ((metal adj substrate) near   | ! IBM_TDB<br>! USPAT;   | 2003/05/14 | 14.57   |
|        |        | core)   | US-PGPUB;               | 2003/03/14 | 14.57   |
|        |        | <del>;</del>  | EPO; JPO;               |            |         |
|        |        | :   | DERWENT;                | 0          |         |
|        | 1.4    | '   | IBM_TDB                 | 2002/05/14 | 16.10 : |
| _      | . 14   | [(("6317331") or ("6097089") or ("5952716")<br>or ("5900675") or ("6028354") or   | USPAT;<br>US-PGPUB;     | 2003/05/14 | 10:18   |
|        | 1<br>1 | ("5672911") or ("5741429")).PN.   | EPO; JPO;               | į.         |         |
| :      | •      |   | DERWENT;                |            | •       |
| 1      | :      |   | IBM_TDB                 |            |         |
| : -    | . 0    | integrated adj circuit and package and metal adj substrate and digital adj ground | USPAT;                  | 2003/05/14 | 16:20   |
|        |        | Herar adj substrate and digital adj ground  | US-PGPUB;<br>EPO; JPO;  |            |         |
|        |        | <br>  | DERWENT;                |            |         |
|        |        |   | IBM_TDB                 | 1          |         |
| -      | 0      | 10/033880   | USPAT;                  | 2003/05/14 | 16:20   |
| 1      | İ      |   | US-PGPUB;               | I          | 1       |
|        | 1      |   | EPO; JPO;<br>! DERWENT; | 1          |         |
| i<br>i |        | ı   | IBM TDB                 |            |         |
| · –    | 29207  | metal adj substrate   | USPAT;                  | 2003/05/15 | 07:58   |
|        |        |   | US-PGPUB;               |            |         |
|        |        | !   | EPO; JPO;               |            |         |
|        |        |   | DERWENT;<br>IBM TDB     |            |         |
|        | 0      | (metal adj substrate ) and digital and  | USPAT;                  | 2003/05/15 | 07:58   |
|        |        | groung  | US-PGPUB;               |            |         |
|        |        |   | EPO; JPO;               |            |         |
|        |        |   | DERWENT;                |            |         |
| _      | 386    | (metal adj substrate ) and digital and  | IBM_TDB<br>USPAT;       | 2003/05/15 | 07.50   |
|        | 200    | ground  | US-PGPUB;               | 2003/03/13 | 01.09   |
|        |        |   | EPO; JPO;               |            |         |
|        |        | <br>  | DERWENT;                |            |         |
|        | 200    | (motal add outletests ) and outletest   | IBM_TDB                 | 2002/05/35 | 07.50   |
| _      | . 300  | (metal adj substrate ) and analog and ground                                      | USPAT;<br>US-PGPUB;     | 2003/05/15 | 07:59   |
| · ·    |        | ground  | EPO; JPO;               |            |         |
|        |        |   | DERWENT;                |            |         |
|        |        |   | IBM_TDB                 | ı          |         |
| · _    | 164    | ((metal adj substrate ) and digital and   |                         | 2003/05/15 | 07:59   |
|        |        | ground) and ((metal adj substrate ) and   | US-PGPUB;               | Į.         |         |
|        |        | analog and ground)  | EPO; JPO;<br>DERWENT;   |            |         |
| •      |        |   | IBM TDB                 |            |         |
| _      | 522    | ((metal adj substrate ) and digital and   | USPAT;                  | 2003/05/15 | 07:59   |
|        |        | ground) or ((metal adj substrate ) and  | US-PGPUB;               |            |         |
| 1      |        | analog and ground)  | EPO; JPO;               |            |         |
|        |        |   | DERWENT;                | •          |         |
| : -    | n :    | :<br>:(((metal adj substrate ) and digital and                                    | IBM_TDB<br>USPAT;       | 2003/05/15 | 08.00   |
| 1      |        | ground) and ((metal adj substrate ) and   | US-PGPUB;               | 1          | 55.55   |
| i      | i      | analog and ground)) and voltage adj rail  | EPO; JPO;               | ;<br>1     |         |
|        | 1      |   | DERWENT;                |            | i       |
| i      | !<br>  |   | IBM_TDB                 | !          | '       |

| i - | 151 | (((metal adj substrate ) and digital and ground) and ((metal adj substrate ) and  | USPAT;<br>US-PGPUB;                           | 72003/05/15     | 08:00  |
|-----|-----|---|---|-----------------|--------|
|     |     | analog and ground)) and voltage   | EPO; JPO; DERWENT; IBM TDB                    |                 | •      |
| -   |     | ((((metal adj substrate ) and digital and ground) and ((metal adj substrate ) and analog and ground)) and voltage ) and digital same ground | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;  | 2003/05/15      | 08:21  |
|     |     | (((((metal adj substrate ) and digital and  | IBM_TDB<br>USPAT:                             | !<br>2003/05/15 | 08-22: |
|     | 2   | ground) and ((metal adj substrate ) and analog and ground)) and voltage ) and digital same ground) and packag\$3                            | US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/03/13      |        |